



APMC 2025

2025 ASIA-PACIFIC MICROWAVE CONFERENCE

DEC 2 - 5, 2025 | ICC JEJU, Jeju Island, Korea

Session Title:	[FE4] Millimeter-Wave Components and Packaging Technologies
Session Date:	December 5 (Fri.), 2025
Session Time:	15:20-17:00
Session Room:	Room E (301)

[FE4-1] [Invited] 15:20-15:40

A Dual-Channel D-Band IQ Receiver with on-Package Antenna and Baseband Polyphase Filter Using Cost-Effective Heterogenous Integration

Ting-Yu Chang, Tian-Wei Huang, Ti-Yu Chao, Shao-Chen Huang, I. Wang and Yu-Hsiang Cheng (National Taiwan University, Taiwan); Jeng-Han Tsai (National Taiwan Normal University, Taiwan)

[FE4-2] 15:40-16:00

Improved Matching of a Chip-to-Waveguide Transition via Cavity Wall Adjustment

Sooyeon Kim (Electronics and Telecommunications Research Institute, Korea (South)); Seung-Hwan Kim (ETRI, Korea (South))

[FE4-3] 16:00-16:20

An Integrated Shield Flip-Chip Mounting MIC Bandpass Filter in Q-Band

Yu Kanamori (JAPAN FINE CERAMICS Company Limited, Japan); Tamotsu Nishino and Noriharu Suematsu (Tohoku University, Japan)

[FE4-4] 16:20-16:40

A GaAs Filter Bank with Wide-Stopband Utilizing Asymmetric Frequency-Division SP7T Switch

Shangsong Ye (University of Electronic Science and Technology of China, China)

[FE4-5] 16:40-17:00

Design and Fabrication of a Decade-Bandwidth 3-30 GHz Quadrature Hybrid Coupler with Discontinuity and Packaging Ingenuity

Taiyo Ushiyama, Mai Sasaki, Tsuyoshi Hazemoto, Sayu Tomioka and Satoshi Ono (The University of Electro-Communications, Japan); Sho Masui and Takafumi Kojima (National Astronomical Observatory of Japan, Japan); Takeshi Sakai (The University of Electro-Communications, Japan)